Compliance list INTEGRATION INSTRUCTIONS for 996369 D03 OEM the and 996369 D03 OEM by Sections 2.2 through 2.10.

Requirement	Yes	N/A	Comment
2.2 List of applicable FCC rules	YES	14,11	Refer to instruction
List the FCC rules that are applicable to the	123		Nerel to instruction
modular transmitter. These are the rules that			FCC standards: FCC CFR Title 47 Part 15
specifically establish the bands of operation,			
, , , , , , , , , , , , , , , , , , , ,			Subpart C Section 15.247
the power, spurious emissions, and operating			
fundamental frequencies. DO NOT list			
compliance to unintentional-radiator rules			
(Part 15 Subpart B) since that is not a			
condition of a module grant that is extended			
to a host manufacturer. See also Section 2.10			
below concerning the need to notify host			
manufacturers that further testing is			
required.3			
2.3 Summarize the specific operational use	YES		Refer to instruction
conditions			
Describe use conditions that are applicable to			Integral antenna with antenna gain 2.5dBi
the modular transmitter, including for			
example any limits on antennas, etc. For			
example, if point-to-point antennas are used			
that require reduction in power or			
compensation for cable loss, then this			
information must be in the instructions. If the			
use condition limitations extend to			
professional users, then instructions must			
state that this information also extends to the			
host manufacturer's instruction manual. In			
addition, certain information may also be			
needed, such as peak gain per frequency band			
and minimum gain, specifically for master			
devices in 5 GHz DFS bands.		21/2	AL
2.4 Limited module procedures		N/A	Not applicable
If a modular transmitter is approved as a			
"limited module," then the module			
manufacturer is responsible for approving the			
host environment that the limited module is			
used with. The manufacturer of a limited			
module must describe, both in the filing and in			
the installation instructions, the alternative			
means that the limited module manufacturer			
uses to verify that the host meets the necessary			
requirements to satisfy the module limiting			
conditions.			
A limited module manufacturer has the			
flexibility to define its alternative method to			
address the conditions that limit the initial			
approval, such as: shielding, minimum			

signaling amplitude, buffered modulation/data inputs, or power supply regulation. The alternative method could include that the limited module manufacturer reviews detailed test data or host designs prior to giving the host manufacturer approval. This limited module procedure is also applicable for RF exposure evaluation when it is necessary to demonstrate compliance in a specific host. The module manufacturer must state how control of the product into which the modular transmitter will be installed will be maintained such that full compliance of the product is always ensured. For additional hosts other than the specific host originally granted with a limited module, at Class II permissive change is required on the module grant to register the additional host as a specific host also approved with the module. 2.5 Trace antenna designs For a modular transmitter with trace antenna designs, see the guidance in Question 11 of KDB Publication 996369 DOZ FAQ – Modules for Micro-Strip Antennas and traces. The integration information shall include for the TCB review the integration information shall include for the TCB review the integration information shall include for the TCB review the integration information shall include for the TCB review the integration information shall include for the TCB review the integration instructions for the following aspects: layout of trace design, parts list (BOM), antenna, connectors, and isolation requirements. a) Information that includes permitted variances (e.g., trace boundary limits, thickness, length, width, shape(s), dielectric constant, and impedance as applicable for each type of antenna); b) Each design shall be considered a different type (e.g., antenna length in multiple(s) of frequency, the wavelength, and antenna shape (traces in phase) can affect antenna gain and must be considered); c) The parameters shall be provided in a namner permitting host manufacturers to design the printed circuit (PC) board layout; d) Appropriate parts by manufacturer and specification		1		
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f) Production test procedures for		
ensuring compliance.		
The module grantee shall provide a		
notice that any deviation(s) from the defined		
parameters of the antenna trace, as described		
by the instructions, require that the host		
product manufacturer must notify the module		
grantee that they wish to change the antenna		
trace design. In this case, a Class II permissive		
,		
change application is required to be filed by		
the grantee, or the host manufacturer can		
take responsibility through the change in FCC		
ID (new application) procedure followed by a		
Class II permissive change application.		
2.6 RF exposure considerations	YES	Refer to instruction
It is essential for module grantees to clearly		
and explicitly state the RF exposure conditions		This modular complies with FCC RF
that permit a host product manufacturer to		radiation exposure limits set forth for an
use the module. Two types of instructions are		uncontrolled environment.
required for RF exposure information: (1) to		
the host product manufacturer, to define the		
application conditions (mobile, portable – xx		
cm from a person's body); and (2) additional		
text needed for the host product		
manufacturer to provide to end users in their		
end-product manuals. If RF exposure		
statements and use conditions are not		
provided, then the host product manufacturer		
is required to take responsibility of the		
module through a change in FCC ID (new		
application).		
	YES	Refer to instruction
2.7 Antennas A list of antennas included in the application	ILJ	Neier to instruction
for certification must be provided in the		Integral antenna with antenna gain 2 EdDi
instructions. For modular transmitters		Integral antenna with antenna gain 2.5dBi
approved as limited modules, all applicable		
professional installer instructions must be		
included as part of the information to the host		
product manufacturer. The antenna list shall		
also identify the antenna types (monopole,		
PIFA, dipole, etc. (note that for example an		
"omni-directional antenna" is not considered to		
be a specific "antenna type")).		
For situations where the host product		
manufacturer is responsible for an external		
connector, for example with an RF pin and		
antenna trace design, the integration		
		•

instructions shall inform the installer that unique antenna connector must be used on the Part 15 authorized transmitters used in the host product. The module manufacturers shall provide a list of acceptable unique connectors. 2.8 Label and compliance information Grantees are responsible for the continued compliance of their modules to the FCC rules. This includes advising host product manufacturers that they need to provide a physical or e-label stating "Contains FCC ID" with their finished product. See Guidelines for Labeling and User Information for RF Devices – KDB Publication 784748.	YES	Refer to instruction If the FCC identification number is not visible when the module is installed inside another device, then the outside of the device into which the module is installed must also display a label referring to the enclosed module. This exterior label can use wording such as the following: "Contains Transmitter Module FCC ID: 2AKS8DX-BT24 Or Contains FCC ID: 2AKS8DX-BT24"
2.9 Information on test modes and additional	YES	
testing requirements ₅		Refer to instruction
Additional guidance for testing host products is given in KDB Publication 996369 D04 Module Integration Guide. Test modes should take into consideration different operational conditions for a stand-alone modular transmitter in a host, as well as for multiple simultaneously transmitting modules or other transmitters in a host product. The grantee should provide information on how to configure test modes for host product evaluation for different operational conditions for a stand-alone modular transmitter in a host, versus with multiple, simultaneously transmitting modules or other transmitters in a host. Grantees can increase the utility of their modular transmitters by providing special means, modes, or instructions that simulates or characterizes a connection by enabling a transmitter. This can greatly simplify a host manufacturer's determination that a module as installed in a host complies with FCC requirements.		Any company of the host device which install this modular with single modular approval should perform the test of radiated & conducted emission and spurious emission,etc. according to FCC part 15C: 15.247 and 15.209 & 15.207,15B Class B requirement, Only if the test result comply with FCC part 15C: 15.247 and 15.209 & 15.207,15B Class B requirement, then the host can be sold legally.
2.10 Additional testing, Part 15 Subpart B	YES	Refer to instruction
The grantee should include a statement that the modular transmitter is only FCC authorized for the specific rule parts (i.e., FCC		Any company of the host device which install this modular with single modular approval should perform the test of radiated & conducted emission and spurious emission,etc. according to FCC part 15C: 15.247 and 15.209 & 15.207,15B Class B requirement, Only if the test result comply with FCC part 15C: 15.247 and 15.209 & 15.207,15B Class B requirement, then the host

transmitter rules) listed on the grant, and that the host product manufacturer is responsible for compliance to any other FCC rules that apply to the host not covered by the modular transmitter grant of certification. If the grantee markets their product as being Part 15 Subpart B compliant (when it also contains unintentional-radiator digital circuity), then the grantee shall provide a notice stating that the final host product still requires Part 15 Subpart B compliance testing with the modular transmitter installed.6

can be sold legally.

When the module is installed inside another device, the user manual of the host must contain below warning statements;

Note: This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

- —Reorient or relocate the receiving antenna.
- —Increase the separation between the equipment and receiver.
- —Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.
- —Consult the dealer or an experienced radio/TV technician for help.